

Active Heat-Loss Compensated Micro-Pirani Gauge for Vacuum Packages

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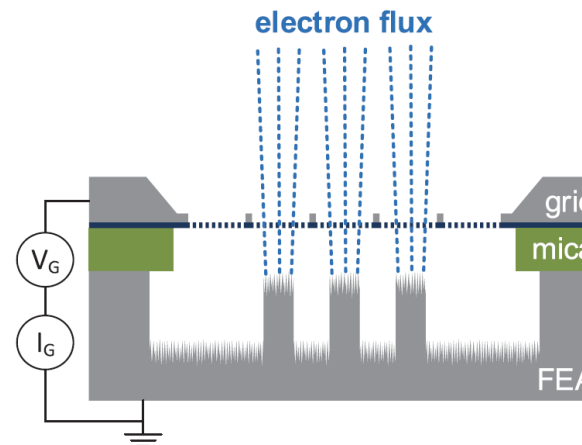
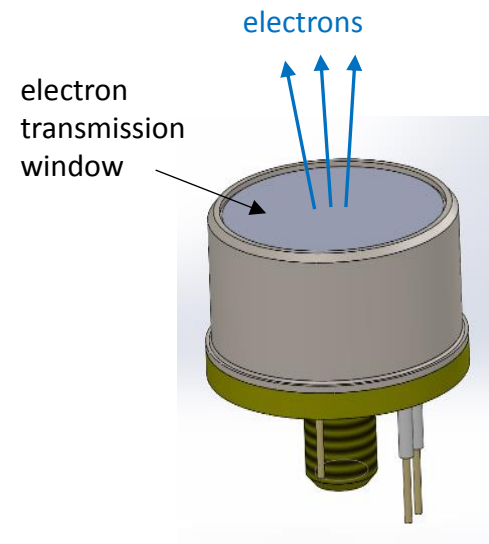
Pressure determination in vacuum package

Several MEMS components or miniaturized MEMS applications require vacuum packaging:

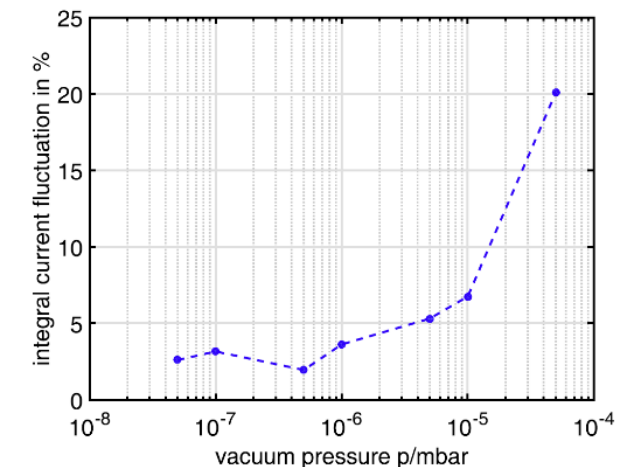
- acceleration sensors
- gyroscope sensors
- micro bolometer
- ...

High vacuum packaging is required for field emission based electron sources or x-ray sources [4]

Vacuum range: $< 10^{-5}$ mbar



[4] M. Bachmann et al. In: J. Vac. Sci. Techn. B 38, 023203 (2020)

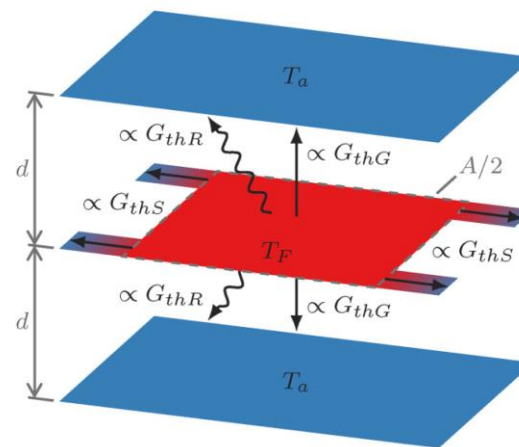


Background: Miniaturized Pirani vacuum gauges

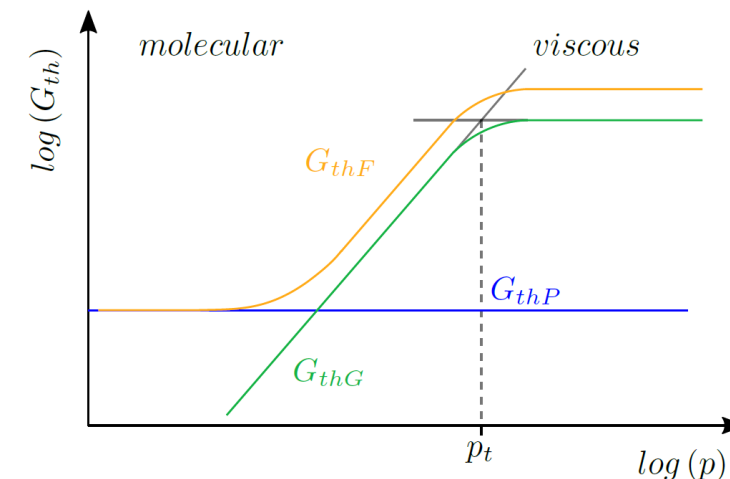
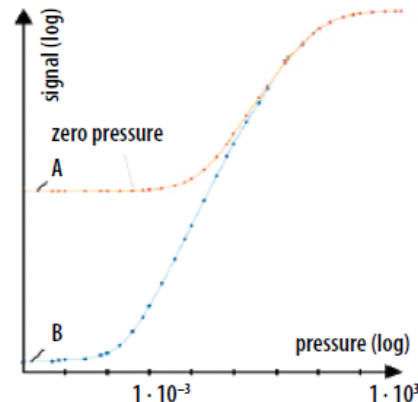
Measuring range: 10^{-5} to 10^3 mbar

$$G_{thF} = G_{thG} + \underbrace{G_{thR} + G_{thS}}_{G_{thP}}$$

At low pressures: G_{thF} dominated by G_{thP}



Reduction of G_{thP} leads to a higher dynamic range and can extend the measuring range to lower pressures



Motivation: Reduction of G_{thP}

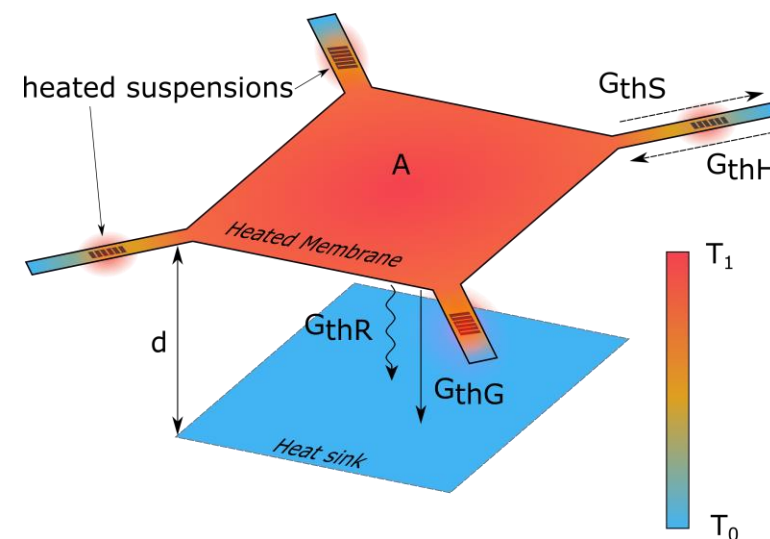
Approaches so far: Passive reduction of G_{thP}

Reduction of G_{thR} : Coating with material of low emissivity (e.g. Au) [1]

Reduction of G_{thS} : Small suspensions, using materials of low thermal conductivity [2,3]

Our approach:

Active heat-loss compensation by additional heating elements located at the suspensions of the sensor membrane

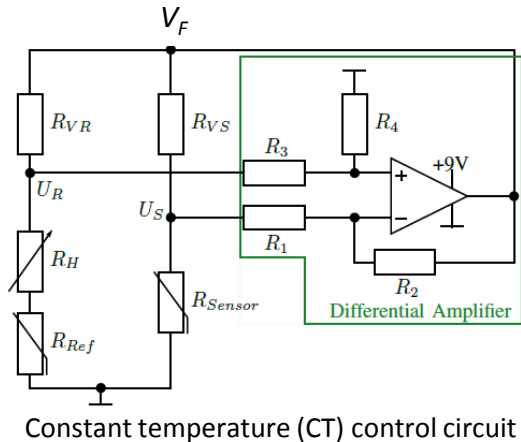


[1] F. Völklein et al. In: J. Vac. Sci. Techn. A 31, 061604 (2013)

[2] H. Miyashita et al. In: Patent US8230746B2 (2011)

[3] L. Gu et al. In: Patent US9335231B2 (2016)

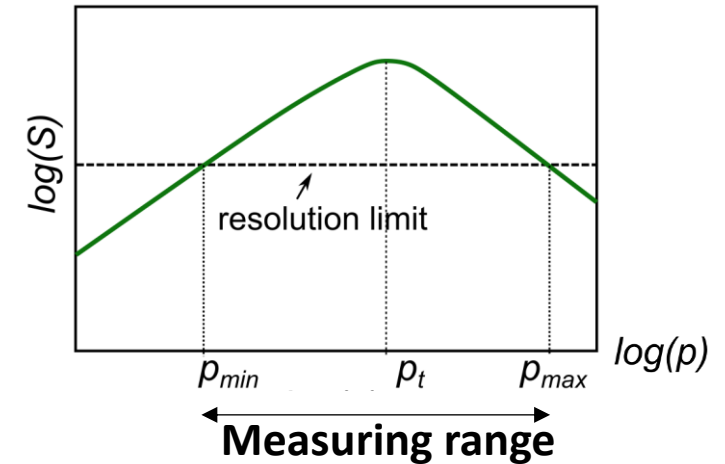
Theory: Influencing factors of Pirani Sensitivity



$$G_{th} = \frac{P_F}{\Delta T} = \frac{V_F^2}{R_0(1 + \alpha(T_0 + \Delta T)) \cdot \Delta T}$$

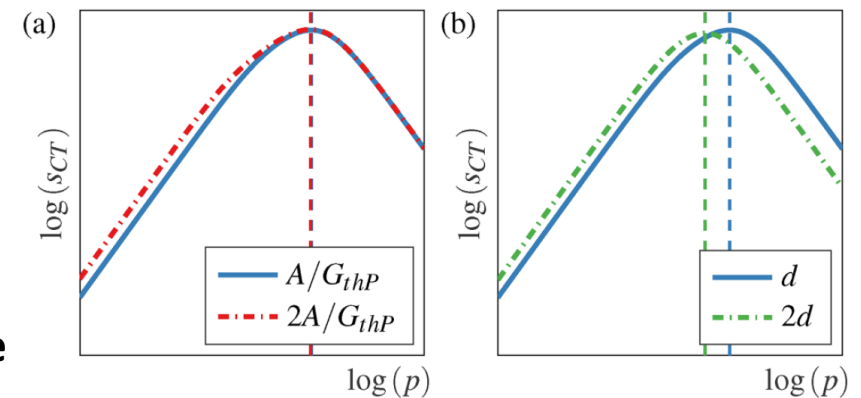
The sensitivity of an instrument is the change of output divided by the change of the measurand

$$S = \frac{\partial V_F}{\partial(\log_{10} p)}$$



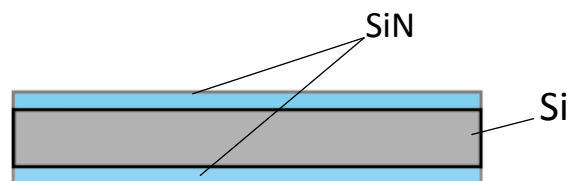
$$S_{norm} = \frac{\ln(10) \frac{\varepsilon A}{G_{thP}} p}{2(\gamma d p + 1)^2 \sqrt{\left(\frac{\varepsilon A}{G_{thP}} \frac{p}{1 + \gamma d p} + 1\right) \left(\frac{\varepsilon A}{G_{thP}} \frac{1}{\gamma d} + 1\right)}}$$

A reduction of G_{thP} leads to a higher sensitivity in the high vacuum regime

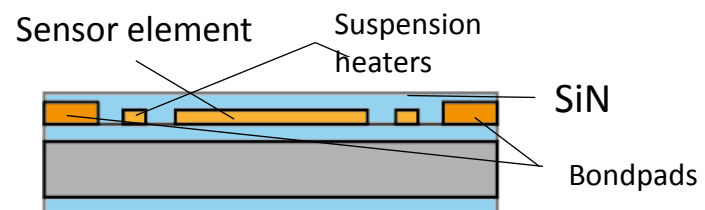


Sensor Design and Fabrication

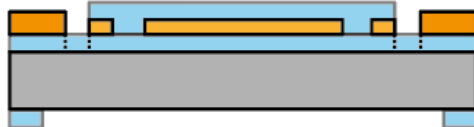
1. Front- and backside SiN deposition (PECVD)



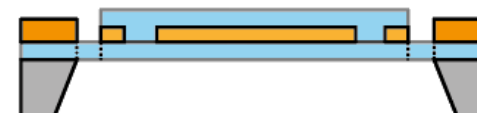
2. Deposition of heater structures and protection layer (photo, PVD, PECVD)



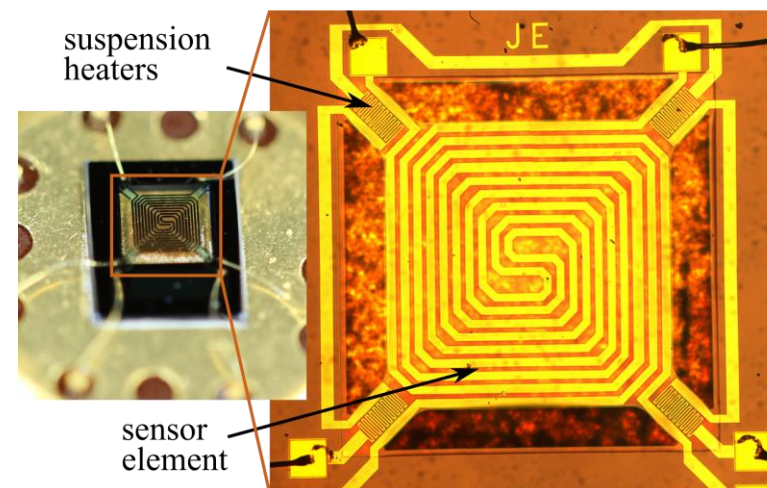
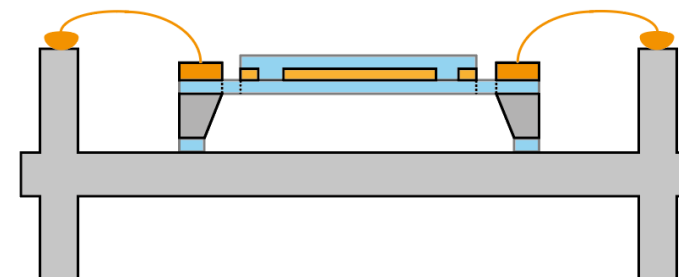
3. Bondpad and backside opening (dry etch)



4. Membrane release (wet etch)



5. Mounting on TO-platform and wire bonding



Experimental Setup : Sensor Operation

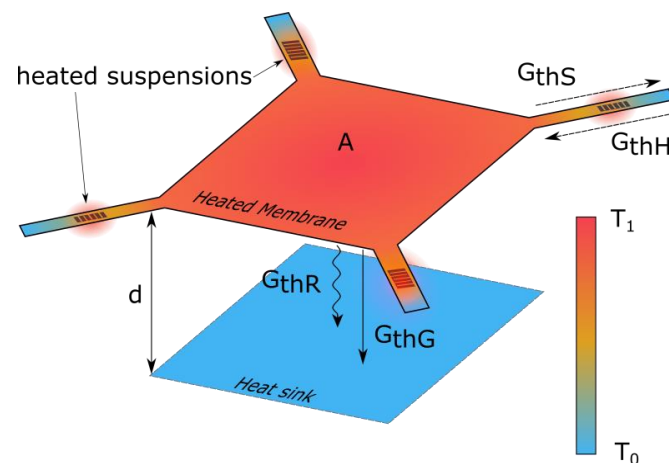
Sensor Element:

Constant Temperature (CT) Circuit

- constant temperature difference
 $\Delta T_{\text{sensor}} = 30^\circ\text{C}$ to the ambient
- Heating power is adapted when pressure changes in order to keep T_{sensor} constant

- V_F as measured quantity of sensor

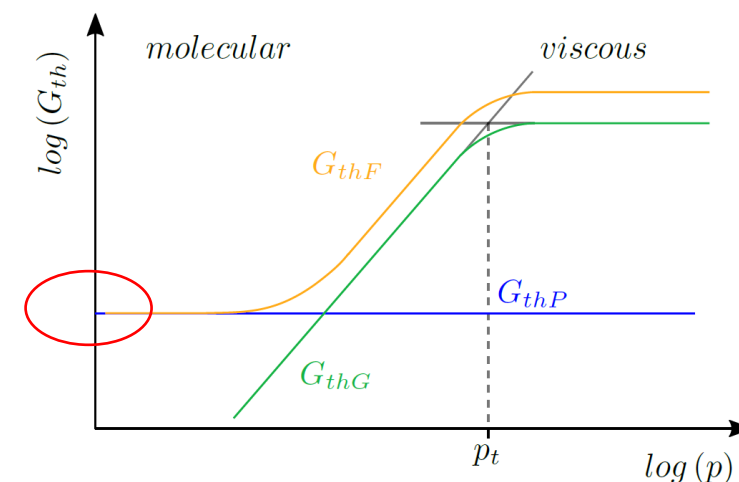
Constant Temperature and Constant Power operations are performed using a **digital PID control**.



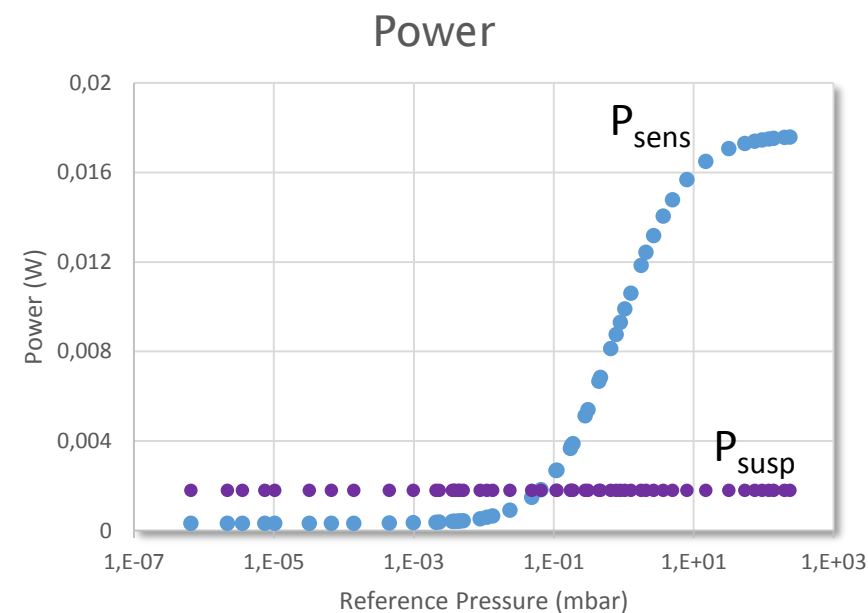
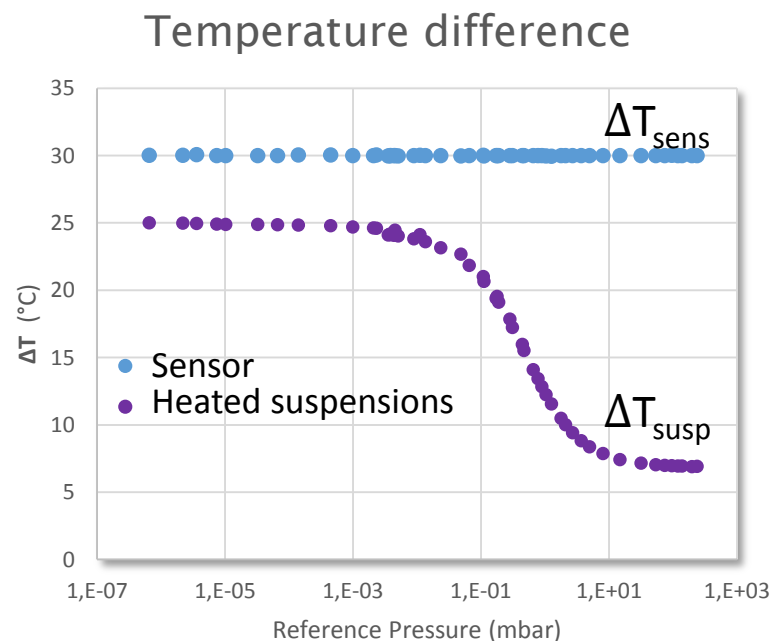
Heated Suspensions: G_{thS} is not pressure dependent

-> Constant Power (CP) Circuit

- at „zero“ pressure $T_{\text{susp}} \approx T_{\text{sensor}}$
- determination of P_{susp} and maintaining throughout measurement to reduce the influence of G_{thS}

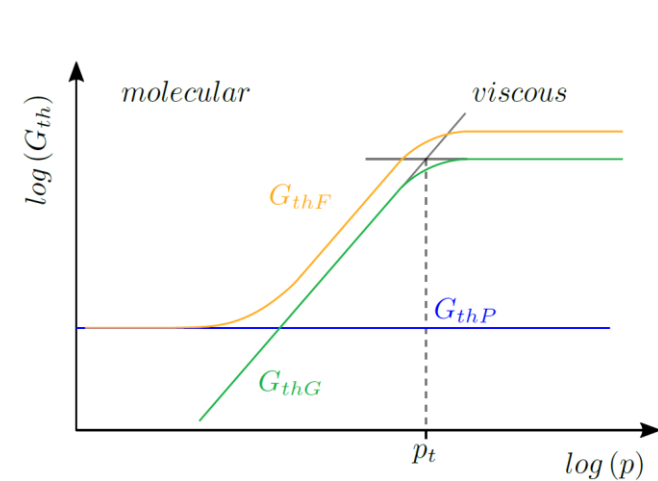


Temperature difference and power during active heat-loss compensation



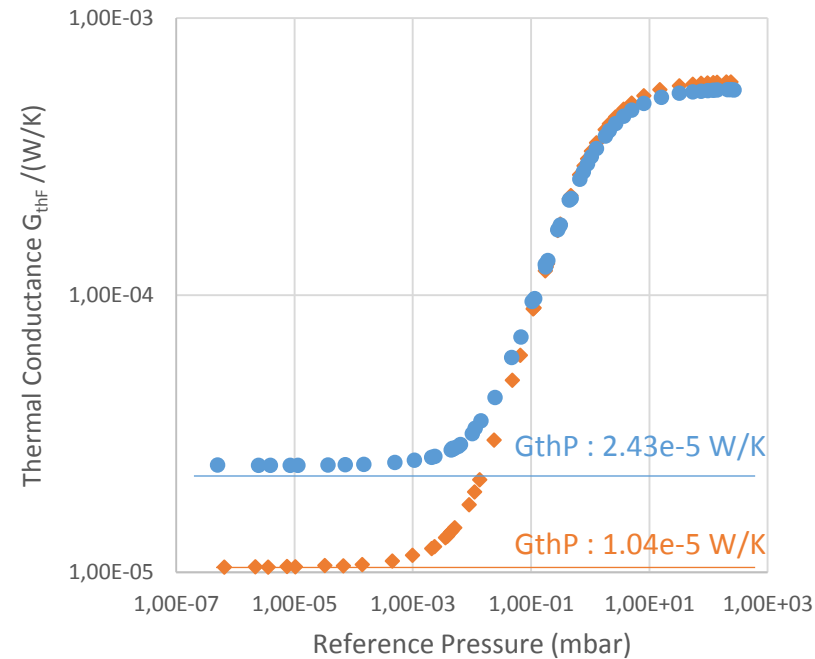
- Sensor temperature T_{sens} is constant (30°C) while power P_{sens} is varied with pressure
- $P_{\text{susp}} = 1.8 \text{ mW}$ is necessary to heat the suspensions to 25°C at “zero” pressure. This power is then maintained throughout the whole pressure region

Thermal conductance

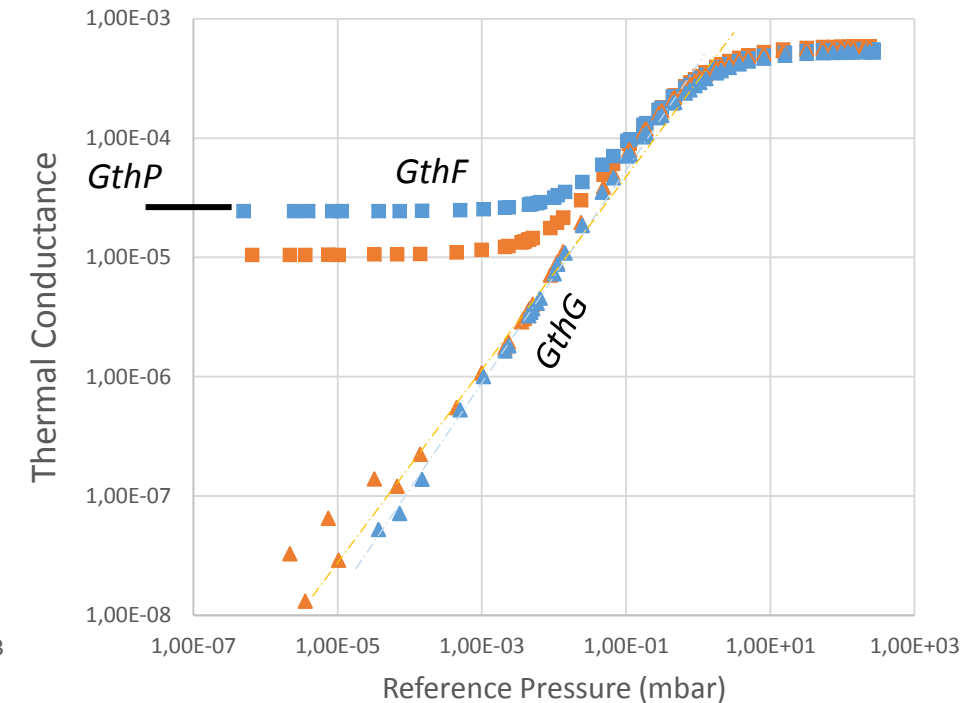


$$G_{thF} = \frac{P_F}{\Delta T}$$

$$G_{thF} = G_{thG} + \underbrace{G_{thR} + G_{thS}}_{G_{thP}}$$



◆ GthF w heated suspensions ● GthF w/o heated suspensions



■ GthF w heated suspensions ■ GthF w/o heated suspensions
▲ GthG w heated suspensions ▲ GthG w/o heated suspensions

- Parasitic heat loss (G_{thP}) is **reduced by over 50%** by implementing heated suspension

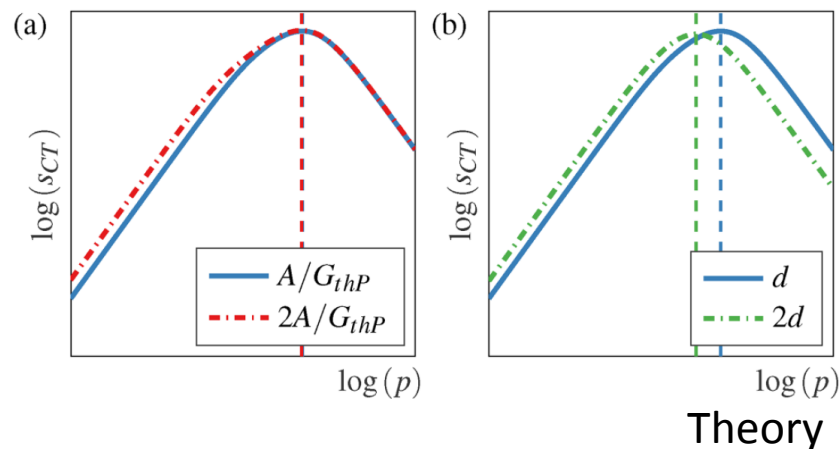
Sensor Sensitivity

Definition of sensitivity based on measured quantity V_F :

$$S = \frac{\partial V_F}{\partial(\log_{10} p)} \quad S_N = \frac{S}{V_{FMAX}}$$

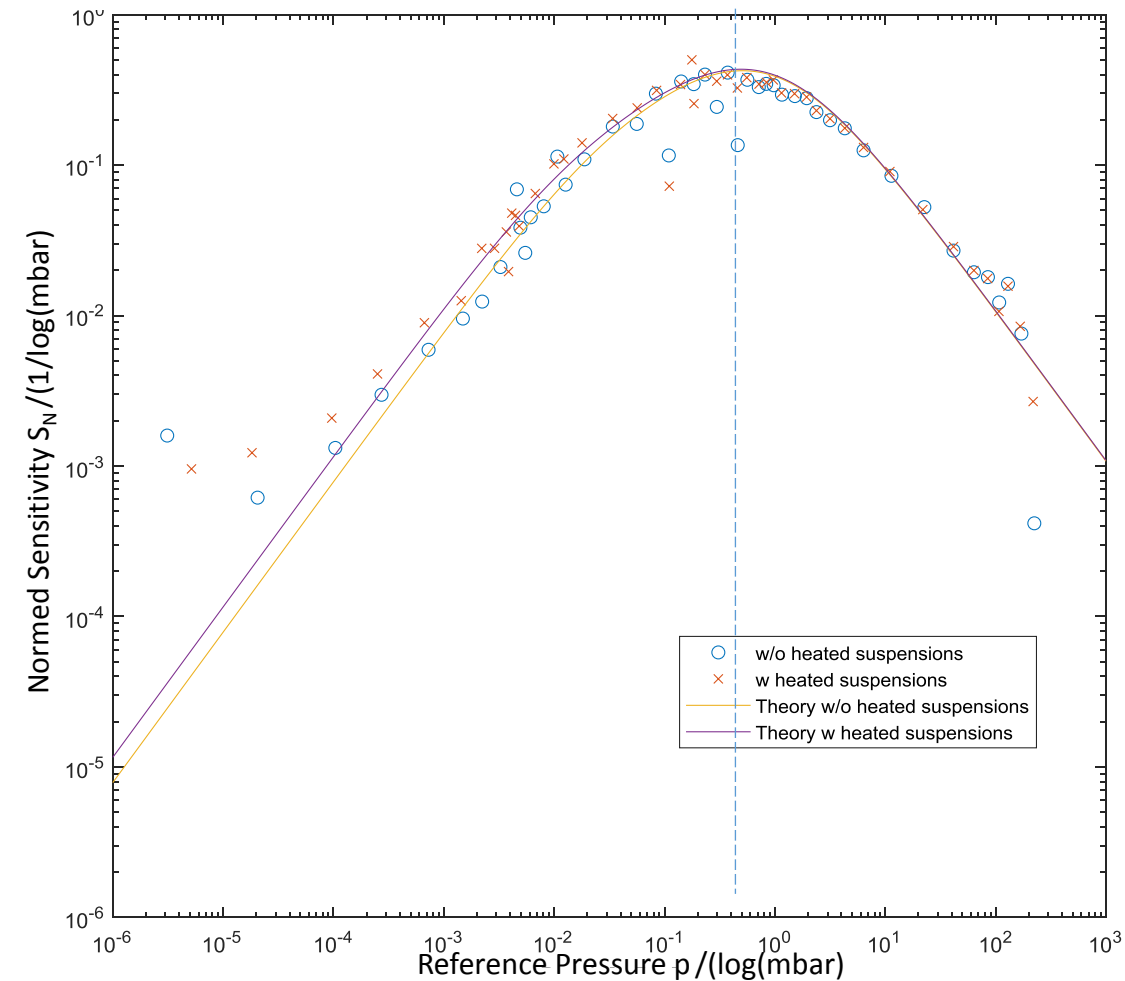
Sensitivity comparison with and without heated suspensions:

- High pressure region ($>10^0$ mbar): Sensitivity is unchanged
- Low pressure region ($<10^0$ mbar): Sensitivity higher with heated suspensions



Experiment

Normalized Sensitivity S_N
Pirani Active Heat Loss Compensation



Conclusion

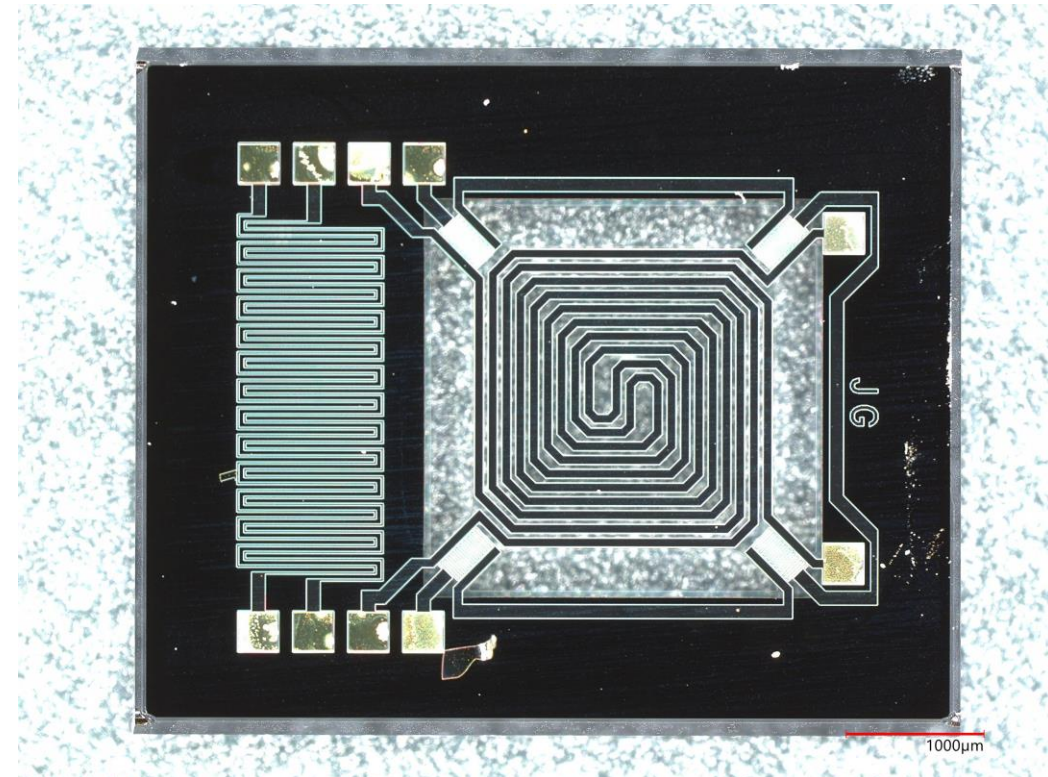
- Heat-loss compensation of Pirani sensors can reduce the parasitic contributions by more than 50%
- Higher dynamic range and improvement of the sensitivity in the low pressure region

Outlook

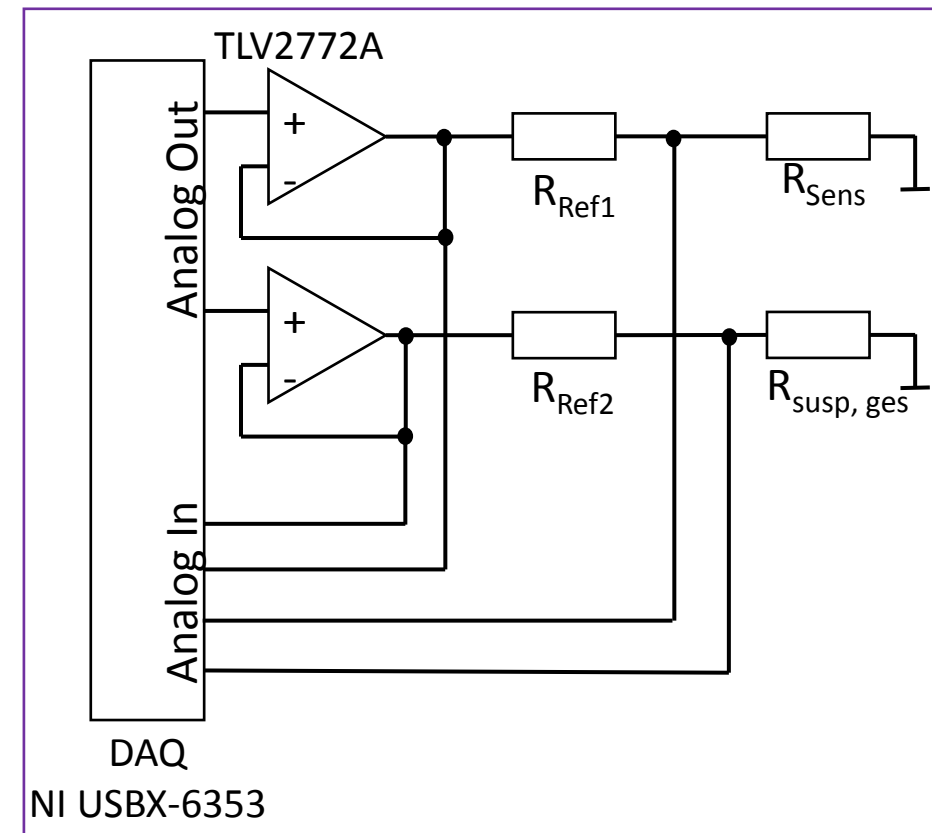
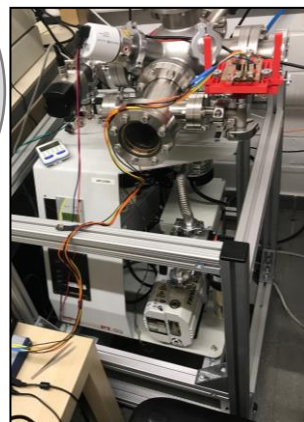
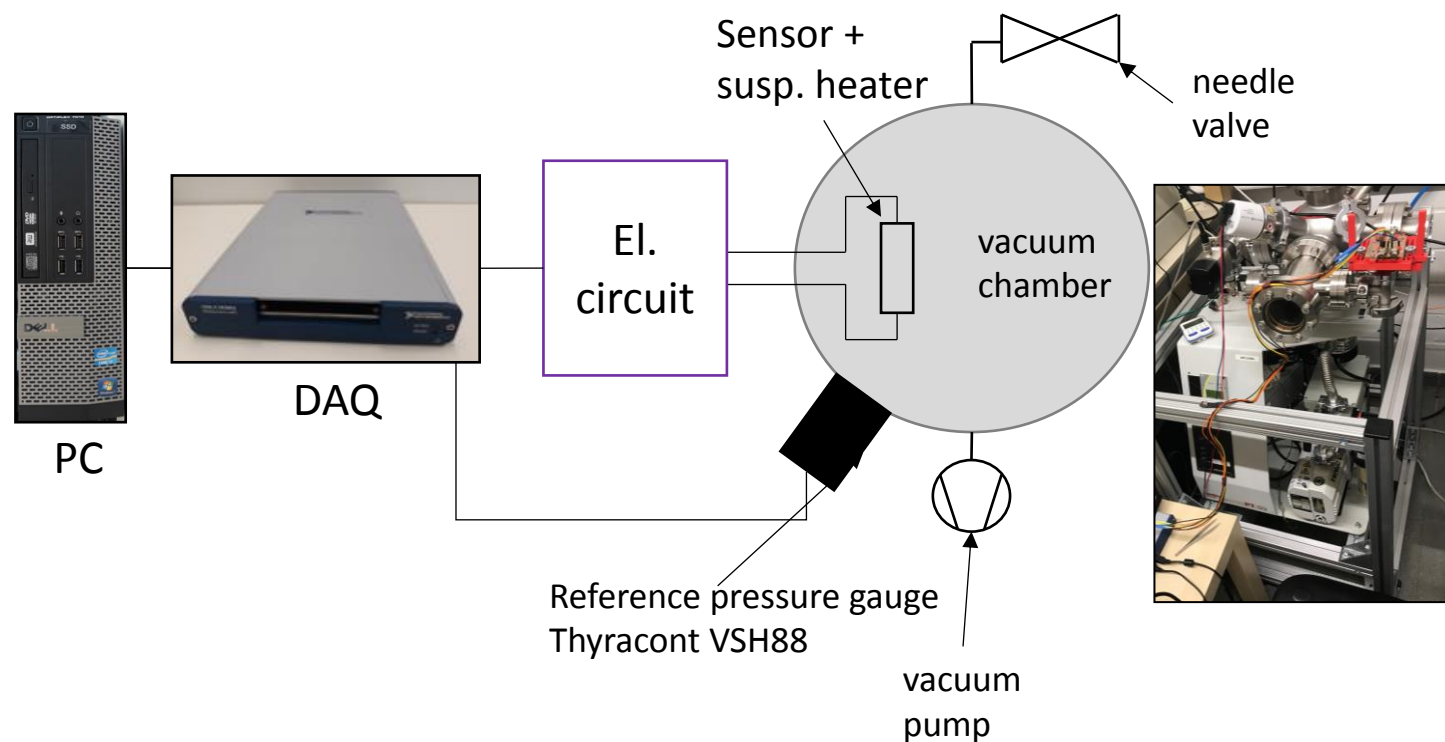
- Implement better electronic circuit to enhance resolution limit
- Further improving sensitivity in low pressure regions by adjusting gap distance to heat sink

Thanks for your attention!

Any questions?



Experimental Setup : Vacuum Chamber and El. Circuit



Theory of thermal conductivity vacuum gauges

$$G_{thF} = \frac{P}{\Delta T}$$

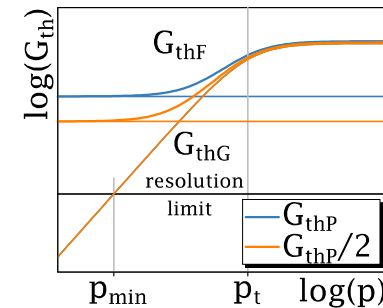
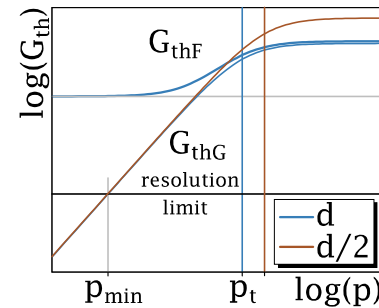
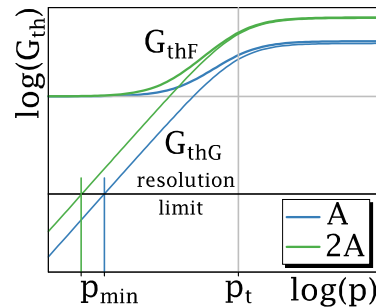
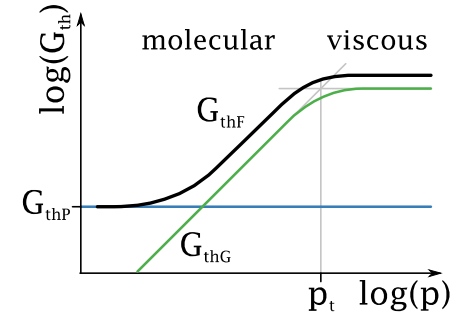
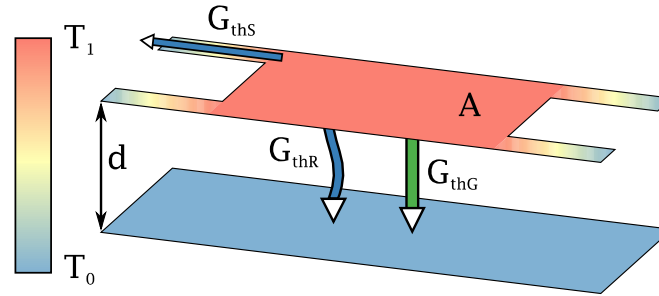
$$G_{thF} = G_{thG} + G_{thP}$$

$$G_{thG} = \lambda_G \frac{A}{d} = \frac{\varepsilon d p}{1 + \gamma d p} \frac{A}{d}$$

$$p < p_t: G_{thG} = \varepsilon A p$$

$$G_{thF} = \frac{P}{\Delta T} = \varepsilon A p + G_{thP}$$

$$p = \frac{1}{\varepsilon A} \left(\frac{P}{\Delta T} - G_{thP} \right)$$



Related Equations

Temperature dependent resistance

$$R = R_0 (1 + \alpha \Delta T)$$

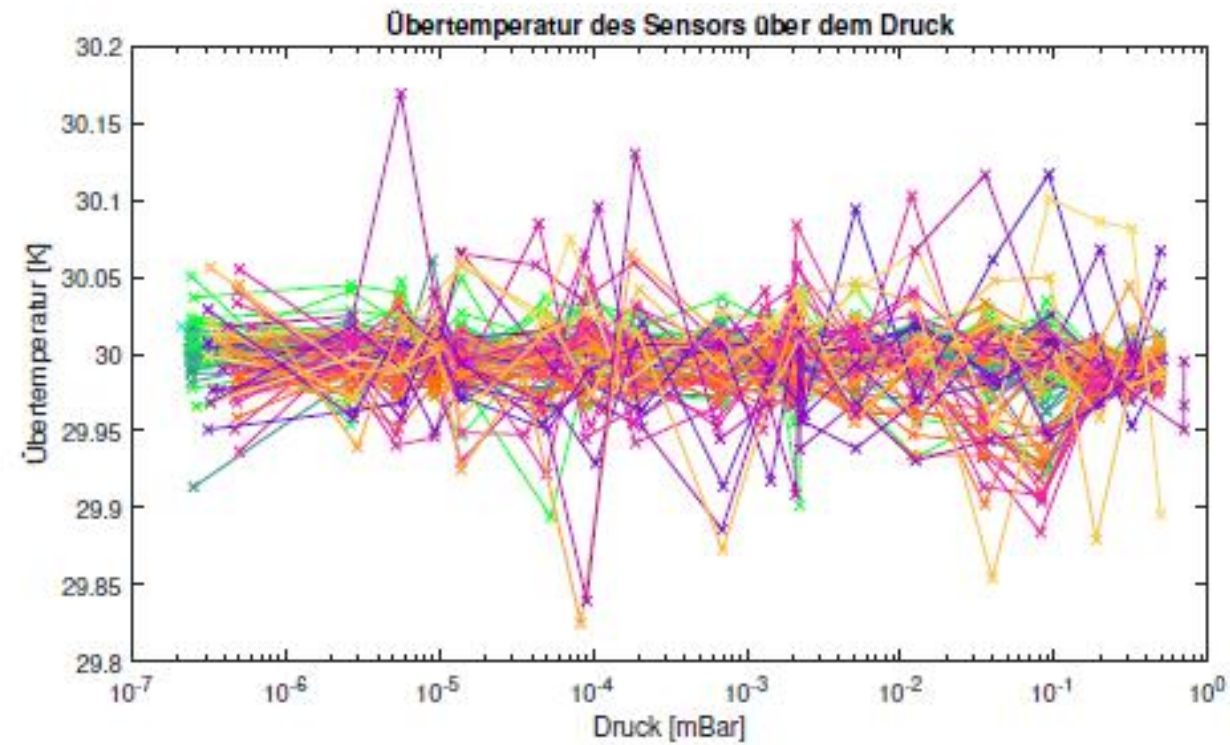
Temperature coefficient of resistance α

$$\alpha = (R_2 - R_1) / R_1 (T_2 - T_1)$$

Heat conductance

$$P_S = G_{TH} \cdot (T_S - T_{amb})$$

$$P_S = (G_g(p) + G_s + G_r) \cdot (T_S - T_{amb})$$



Sensitivity definition by change of thermal conductance $\Delta G_{tHF} / \Delta \log(P)$

